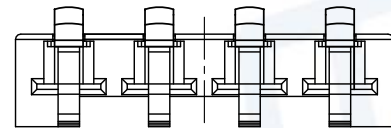
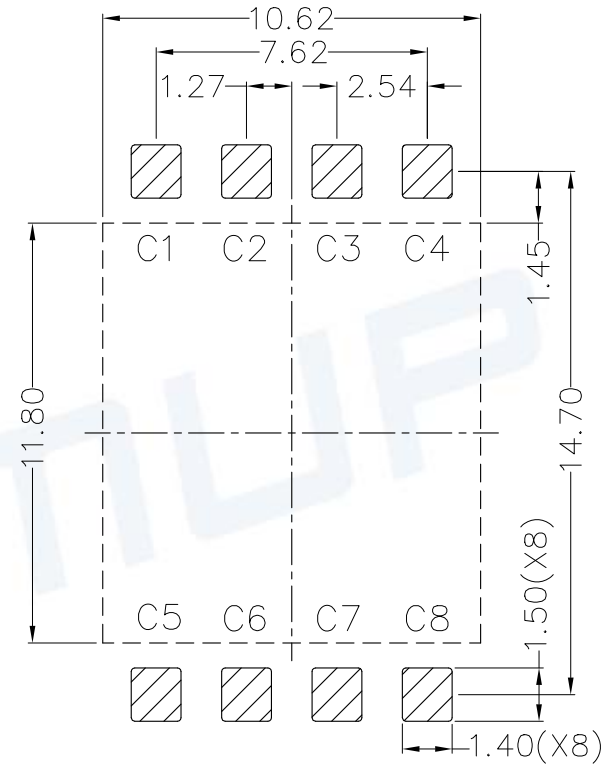


SECTION A-A



REV.	DESCRIPTION OF REVISIONS	APPR.	DRAW.	RELEASE	DATE
X1					
X2					



RECOMMENDED P.C.B LAYOUT
COMPONENT SIDE(TOLERANCE ±0.05)

SIM CARD

Pin No.	NAME
C1	VCC
C2	RST
C3	CLK
C4	Reserved
C5	GND
C6	VPP
C7	I/O
C8	Reserved

TECHNICAL CHARACTERISTICS

1.General Characteristics

Dimensions: 11.80LX10.62WXH mm
H=2.60 mm
Durability: 5,000 cycles min.

2.Electrical Characteristics

Contact resistance: 50mΩ typical, 100mΩ max
Insulation resistance: >1000MΩ/500V DC

3.Solderability

Vaporphase: 215°C, 30sec.Max
IR reflow: 250°C, 5sec.Max
Manual soldering: 370°C, 3sec.Max

4.Environmental Characteristics

Operating temperature: -40°C~+85°C
Operating humidity: 10%~+95%RH

ITEM	PART NAME	Q'TY	MATERIAL	FINISH
1	HOUSING	1	Hi-temp Thermoplastic	Black UL94V-0
2	DATA CONTACT	8	Copper Alloy	Contact area: Gold plated

Unless otherwise specified, other tolerance are:

MUP MUP INDUSTRIAL CO.,LTD.

NAME: **SIM Card Connector**

MODEL NO: **MUP C733-3**

TYPE: **H2.6 without post 8p**

PROJ.	UNIT	SCALE	DRAWN	Zoey Dec.07.2009	DWG NO.:	DWG-MUP-C733-003
	mm	1:1	CHECKED	Jimmy Dec.07.2009	SHEET	1/1
CUSTOMER DRAWING			APPROVAL	Jun Dec.07.2009	REVISION	X1

